#### SN5496, SN54LS96, SN7496, SN74LS96 **5-BIT SHIFT REGISTERS**

SDLS946 - MARCH 1974 - REVISED MARCH 1988

- N-Bit Serial-To-Parallel Converter
- N-Bit Parallel-To-Serial Converter
- N-Bit Storage Register

TYPICAL

TYPE PROPAGATION TYPICAL DELAY TIME POWER DISSIPATION

'96 25 ns 240 mW 25 ns 60 mW

'LS96 description

> These shift registers consist of five R-S master-slave flip-flops connected to perform parallel-to-serial or serial-to-parallel conversion of binary data. Since both inputs and outputs for all flip-flops are accessible, parallel-in/parallel-out or serial-in/serial-out operation may be performed.

All flip-flops are simultaneously set to a low output level by applying a low-level voltage to the clear input while the preset is inactive (low). Clearing is independent of the level of the clock input.

The register may be parallel loaded by using the clear input in conjunction with the preset inputs. After clearing all stages to low output levels, data to be loaded is applied to the individual preset inputs (A, B, C, D, and E) and a high-level load pulse is applied to the preset enable input. Presetting like clearing is independent of the level of the clock input.

Transfer of information to the outputs occurs on the positive-going edge of the clock pulse. The proper information must be set up at the R-S inputs of each flip-flop prior to the rising edge of the clock input waveform. The serial input provides this information to the first flip-flop, while the outputs of the subsequent flip-flops provide information for the remaining R-S inputs. The clear input must be high and the preset or preset enable inputs must be low when clocking occurs.

#### FUNCTION TABLE

	INPUTS									OUTPUTS						
CLEAR	PRESET	Г	PI	ES	ET					_	628	723				
CLEAR	ENABLE	A	В	С	۵	E	CLOCK	SERIAL	QA.	OB.	αc	ΦĎ	αD			
L	L	х	Х	х	X	X	×	х	L	L	L	L	L			
L	×	L	L	L	L	Ł	×	x	L	L	L	L	L			
н	н	н	н	H	н	н	×	×	н	н	H	н	н			
н	н	L	ι	L,	L	L	L	x	QAO	OBO	aco	apo	QEO			
н	н	н	L	H	L	H	L	х	н	QBO	H	QDO	н			
н	L	×	X	X	X	X	L	×	GAO	080	QCO	QDO	QEO			
н	L	x	X	X	X	x	t	н	н	QAn	QBn	acn	apn			
н	L	×	X	X	×	×	1	L	L	QAn	QRo	Qca	Qna			

- H = high level (steady state), L = low level (steady state)

- the implified in second states, L = into leaver states by state)

  X = irrelevant (any input, including transistion)

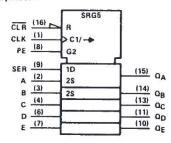
  1 = transistion from low to high level

  2A<sub>0</sub>. O<sub>B0</sub>, etc. = the level of O<sub>A</sub>. O<sub>B</sub>, etc. respectively before the indicated steadystate input conditions were established.
- $Q_{An},\,Q_{Bn},\,$  etc. the level of  $Q_{A},\,Q_{B},\,$  etc. respectively before the most recent  $\,$  † transistion of the clock.

SN5496, SN54LS96 . . . J OR W PACKAGE SN7496 . . . N PACKAGE SN74LS96 . . . D OR N PACKAGE (TOP VIEW)

CLK [	U <sub>16</sub>	CLR
A [	15	$\Box Q_{A}$
в□з	14	]Q <sub>B</sub>
c []∢	13	$\Box a_{C}$
Vcc [	12	GND
DQ	11	$\Box a_{D}$
E []	10	οĘ
PRE DE	9	SER

#### logic symbol<sup>†</sup>

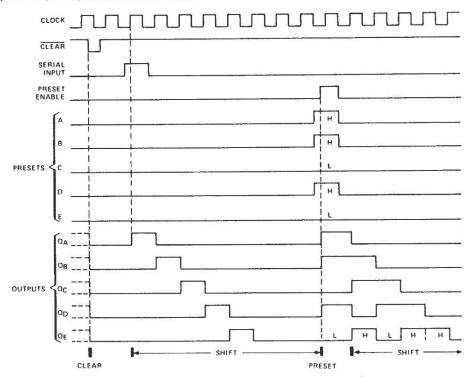


<sup>†</sup>This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

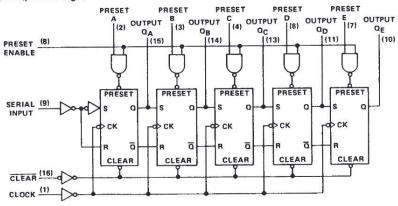
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typical clear, shift, preset, and shift sequences

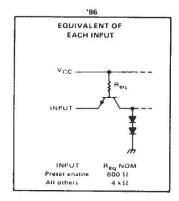


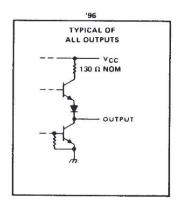
logic diagram (positive logic)

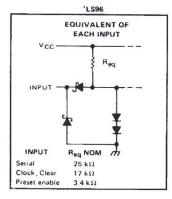


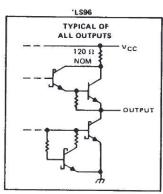


### schematics of inputs and outputs









# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)
Input voltage (see Note 2): '96
'LS96
Operating free-air temperature: SN54'55°C to 125°C
SN74' 0°C to 70°C
Storage temperature range65°C to 150°C

- NOTES: 1. Voltage values are with respect to network ground terminal.
  - 2. Input voltage must be zero or positive with respect to network ground terminal.



#### recommended operating conditions

	SN5496				SN7498			
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Supply voltage, VCC	4.5	5	5.5	4.75	5	5.25	V	
High-level output current, IOH			-400	Γ		-400	μА	
Low-level output current, IOL			16			16	mA	
Clock frequency, fclock	0		10	0		10	MHz	
Width of clock input pulse, tw(clock)	35	er-10 1010		35			ns	
Width of preset and clear input pulse, tw	30		201 20200	30	- 1746345- 16		ns	
Serial input setup time, t <sub>SU</sub> (see Figure 1)	30		207	30			ns	
Serial input hold time, th (see Figure 1)	0			0			ns	
Operating free-air temperature, TA	-55		125	0		70	°c	

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER		TEST CO		SN5496		SN7496			UNIT	
	PAHAMETER	TEST CO	MIN	TYP	MAX	MIN	TYP‡	MAX	UNIT		
VIH	High-level input voltage				2			2			٧
VIL	Low-level input voltage		N 10 7 10 7				0.8		1 1858 - C	8.0	V
۷он	High-level output voltage	V <sub>CC</sub> = MIN, V <sub>IL</sub> = 0.8 V,	V <sub>1H</sub> = 2 V, I <sub>OH</sub> = -400 μA	2.4	3.4		2.4	3.4		V	
VOL	Low-level output voltage		V <sub>CC</sub> = MIN, V <sub>IL</sub> = 0.8 V,	V <sub>IH</sub> = 2 V, I <sub>OL</sub> = 16 mA		0.2	0.4		0.2	0.4	٧
l <sub>1</sub>	Input current at maximum	input voltage	VCC = MAX,	V <sub>1</sub> = 5.5 V	1		1			1	mA
		any input except preset enable	VCC - MAX.	V1 = 2.4 V			40			40	μΑ
		preset enable				200			200	ī	
T		any input except preset enable	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 0.4 V			-1.6			-1.6	mA
		preset enable					-8			-8	
los	Short-circuit output current§		V <sub>CC</sub> = MAX		-20		-57	-18		-57	mA
1cc	Supply current	VCC = MAX,	See Note 3	1 22	48	68		48	79	mA	

For conditions shown at MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.

§ Not more than one output should be shorted at a time.

NOTE 3: I<sub>CC</sub> is measured with the clear input grounded and all other inputs and outputs open.

### switching characteristics, VCC = 5 V, $TA = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
tpLH Propaga	ition delay time, low-to-high-level output from clock	C <sub>I</sub> = 15 pF,	s 20000	25	40	ns
tPHL Propaga	ition delay time, high-to-low-level output from clock	R <sub>1</sub> = 400 Ω.		25	40	ns
tPLH Propaga	ation delay time, low-to-high-level output from preset or preset enable	See Figure 1		28	35	ns
tpHL Propaga	ition delay time, high-to-low-level output from clear	See rigure i			55	ns

#### recommended operating conditions

	SN54LS96			S			
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, VCC	4.5	5	5.5	4.75	5	5.25	٧
High-level output current, IOH			-400			-400	μА
Low-level output current, IOL			4			8	mA
Clock frequency, fclock	0	2110000	25	0		25	MHz
Width of clock input pulse, tw(clock)	20			20	9-70-70-70-70-70-70-70-70-70-70-70-70-70-		ns
Width of preset and clear input pulse, tw	30			30			ns
Serial input setup time, I <sub>setup</sub> (see Figure 1)	30	anconsociones		30			ns
Serial input hold time, thold (see Figure 1)	0			0			ns
Operating free-air temperature, TA	~55		125	0		70	"C

#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

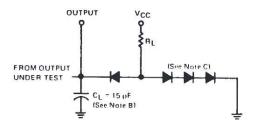
	040445	***			int	S	N54 LS	96	S	96		
	PARAME	IEH	TEST CONDITIONS†			MIN	TYP	MAX	MIN	TYPI	MAX	UNIT
VIH	High-level input vi	oitage				2	section and a revenue		2			V
VIL	Low-level input vo	oltage						0.7		Liberton Company	0.8	V
VIK	Input clamp volta	ge	VCC = MIN,	I <sub>1</sub> = -18 mA				-1.5			-1.5	V
Vон	High-level output	output voltage   V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V,   V <sub>IL</sub> = V <sub>IL</sub> max, I <sub>OH</sub> = -400 µA				2.5	3.5		2.7	3.5		v
VOL Low-level output voltage			VCC = MIN,	VIH = 2 V,	IQL = 4 mA		0.25	0.4		0.25	0.4	V
AOL com-level on that voltage		vortage	VIL * VIL max	VIL * VIL max						0.35	0.5	_
1963	Input current at maximum	Preset enable	V <sub>CC</sub> = MAX, V <sub>I</sub> = 7 V					0.5			0.5	mA
11	input voltage	All others	- VCC - MAX, VI - / V				0.1			0,1		
l	High-level	Preset enable	V <sub>CC</sub> = MAX,	V. = 27 V				100		/->>>>	100	μА
ΉΗ	input current	All others	-ce man: 11 2.5			20					20	
ā.	Low-level	Preset enable	1/ 11 A V	V = 0.4 V				-2			-2	mA
IL input current		All others	V <sub>CC</sub> = MAX, V <sub>1</sub> = 0.4 V			-0.4				-0.4	1117	
los	Short-circuit outp	out current \$	VCC = MAX			-20		-100	-20		100	mA
Icc	Supply current		VCC = MAX,	See Note 3			12	20	2000 2000	12	20	mA

### switching characteristics, VCC = 5 V, TA = 25°C

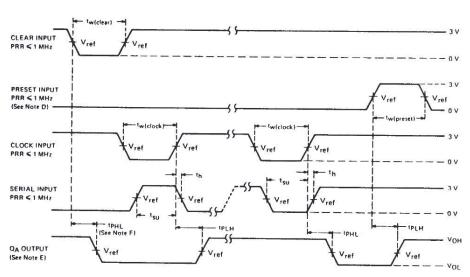
PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
tPLH Propagation delay time, low-to-high-level output from clock	C - 15 - C		25	40	ns
PHL Propagation delay time, high-to-low-level output from clock	CL = 15 pF,		25	40	ns
PLH Propagation delay time, low-to-high-level output from preset or preset enable	R <sub>L</sub> = 2 kΩ, See Figure 1		28	35	ns
tPHL Propagation delay time, high-to-low-level output from clear	See Figure 1		1000000	55	ns

For conditions shown at MIN or MAX, use the appropriate value specified under recommended operating conditions. If typical values are at  $V_{\rm CC}$  = 5 V,  $T_{\rm A}$  = 25 C Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second. NOTE 3:  $T_{\rm CC}$  is measured with the clear input grounded and all other inputs and outputs open.

#### PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT



**VOLTAGE WAVEFORMS** 

NOTES: A. Input pulses are supplied by pulse generators having the following characteristics: duty cycle  $\leq$  50%,  $Z_{out} \approx$  50  $\Omega$ ; for '96,  $t_f \leq$  10 ns,  $t_f \leq$  10 ns, and for 'LS96  $t_f =$  15 ns,  $t_f =$  6 ns.

- B. CL includes probe and jig capacitance. C. All diodes are 1N3064 or equivalent.
- D. Preset may be tested by applying a high-level voltage to the individual preset inputs and pulsing the preset enable or by applying a high-level voltage to the preset enable and pulsing the individual preset inputs.
   E. OA output is illustrated. Relationship of serial input to other Q outputs is illustrated in the typical shift sequence.
- F. Outputs are set to the high level prior to the measurement of tpHL from the clear input. G. For '96,  $V_{ref} = 1.5$  V; for 'LS96  $V_{ref} = 1.3$  V.

FIGURE 1-SWITCHING TIMES





11-Apr-2013

#### PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
SN5496J	OBSOLETE	CDIP	J	16	TBD	Call TI	Call TI	-55 to 125		
SN7496N	OBSOLETE	PDIP	N	16	TBD	Call TI	Call TI	0 to 70		
SN74LS96D	OBSOLETE	SOIC	D	16	TBD	Call TI	Call TI	0 to 70		
SN74LS96DR	OBSOLETE	SOIC	D	16	TBD	Call TI	Call TI	0 to 70		
SN74LS96J	OBSOLETE	CDIP	J	16	TBD	Call TI	Call TI	0 to 70		
SN74LS96N	OBSOLETE	PDIP	N	16	TBD	Call TI	Call TI	0 to 70		
SN74LS96N3	OBSOLETE	PDIP	N	16	TBD	Call TI	Call TI	0 to 70		
SNJ5496J	OBSOLETE	CDIP	J	16	TBD	Call TI	Call TI	-55 to 125		
SNJ5496W	OBSOLETE	CFP CFP	W	16	TBD	Call TI	Call TI	-55 to 125		

(1) The marketing status values are defined as follows: ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design. PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): Tl's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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### PACKAGE OPTION ADDENDUM



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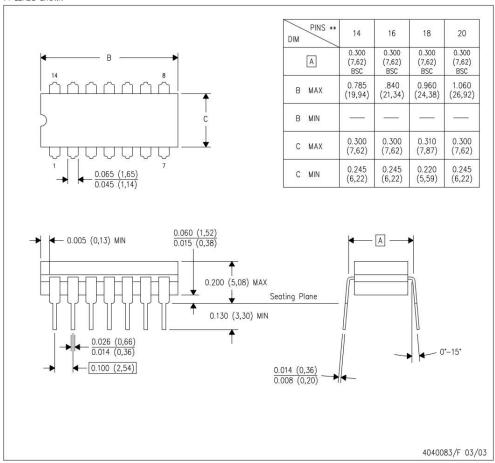
Catalog: SN7496

Military: SN5496

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

14 LEADS SHOWN



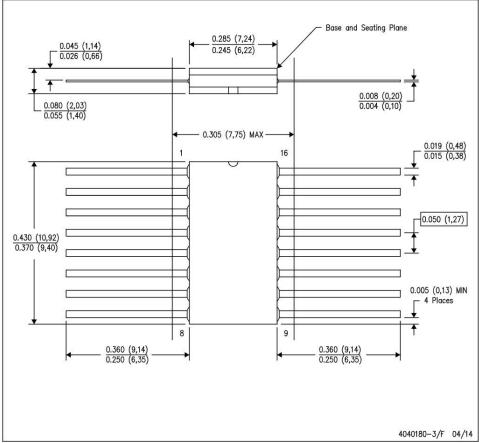
NOTES:

- A. All linear dimensions are in inches (millimeters).

  B. This drawing is subject to change without sales. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

## W (R-GDFP-F16)

### CERAMIC DUAL FLATPACK



NOTES:

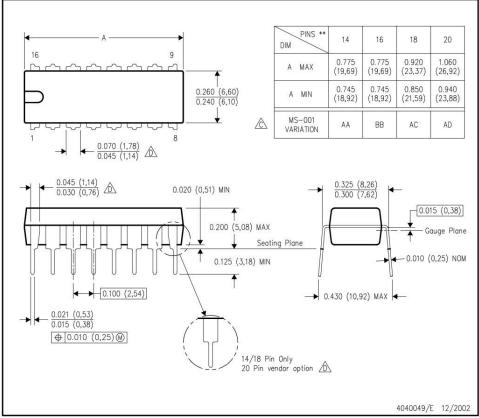
- A. All linear dimensions are in inches (millimeters).

  B. This drawing is subject to change without notice.
  C. This package can be hermetically sealed with a ceramic lid using glass frit.
  D. Index point is provided on cap for terminal identification only.
  E. Falls within MIL STD 1835 GDFP2-F16



# N (R-PDIP-T\*\*)

### PLASTIC DUAL-IN-LINE PACKAGE

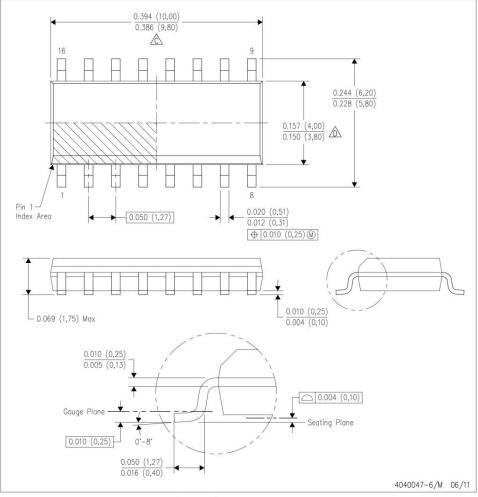


- All linear dimensions are in inches (millimeters). This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



### D (R-PDSO-G16)

### PLASTIC SMALL OUTLINE



NOTES:

- All linear dimensions are in inches (millimeters). This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.

  Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.

  E. Reference JEDEC MS-012 variation AC.



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